

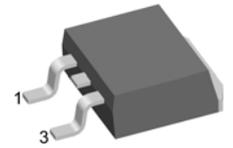
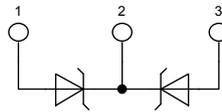
Schottky Diode

High Performance Schottky Diode
Low Loss and Soft Recovery
Common Cathode

$V_{RRM} = 30\text{ V}$
 $I_{FAV} = 2 \times 25\text{ A}$
 $V_F = 0.35\text{ V}$

Part number

DSSK48-003BS



Backside: cathode

Features / Advantages:

- Very low V_f
- Extremely low switching losses
- low I_{rm} values
- Improved thermal behaviour
- High reliability circuit operation
- Low voltage peaks for reduced protection circuits
- Low noise switching

Applications:

- Rectifiers in switch mode power supplies (SMPS)
- Free wheeling diode in low voltage converters

Package:

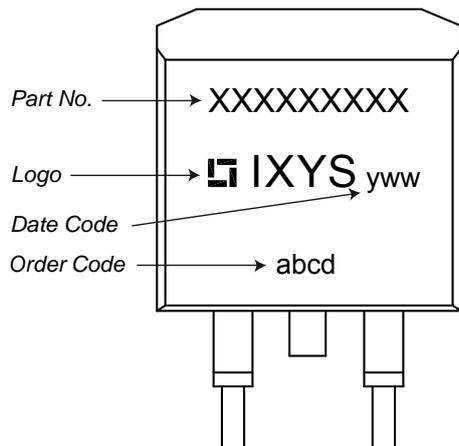
- Housing: TO-263 (D2Pak)
- Industry standard outline
- Epoxy meets UL 94V-0
- RoHS compliant

| Symbol | Definition | Conditions | Ratings | | | Unit | |
|------------|-------------------------------------|--------------------------------------|------------------------------|------|------|------|---|
| | | | min. | typ. | max. | | |
| V_{RRM} | max. repetitive reverse voltage | | | | 30 | V | |
| I_R | reverse current | $V_R = 30\text{ V}$ | | | 20 | mA | |
| | | $V_R = 30\text{ V}$ | | | 60 | mA | |
| V_F | forward voltage | $I_F = 20\text{ A}$ | | | 0.44 | V | |
| | | $I_F = 40\text{ A}$ | | | 0.54 | V | |
| | | $I_F = 20\text{ A}$ | $T_{VJ} = 125^\circ\text{C}$ | | | 0.35 | V |
| | | $I_F = 40\text{ A}$ | $T_{VJ} = 125^\circ\text{C}$ | | | 0.48 | V |
| I_{FAV} | average forward current | rectangular d = 0.5 | | | 25 | A | |
| V_{F0} | threshold voltage | } for power loss calculation only | | | 0.19 | V | |
| r_F | slope resistance | | | | 6.8 | mΩ | |
| R_{thJC} | thermal resistance junction to case | | | | 1.20 | K/W | |
| T_{VJ} | virtual junction temperature | | -55 | | 150 | °C | |
| P_{tot} | total power dissipation | | | | 105 | W | |
| I_{FSM} | max. forward surge current | t = 10 ms (50 Hz), sine | | | 300 | A | |
| C_J | junction capacitance | $V_R = 5\text{ V}; f = 1\text{ MHz}$ | | 1.77 | | nF | |

| Symbol | Definition | Conditions | Ratings | | | Unit |
|---------------|-------------------------------------|-----------------------|---------|------|------|------|
| | | | min. | typ. | max. | |
| I_{RMS} | RMS current | per pin ¹⁾ | | | 35 | A |
| R_{thCH} | thermal resistance case to heatsink | | | 0.25 | | K/W |
| T_{stg} | storage temperature | | -55 | | 150 | °C |
| Weight | | | | 2 | | g |
| F_c | mounting force with clip | | 20 | | 60 | N |

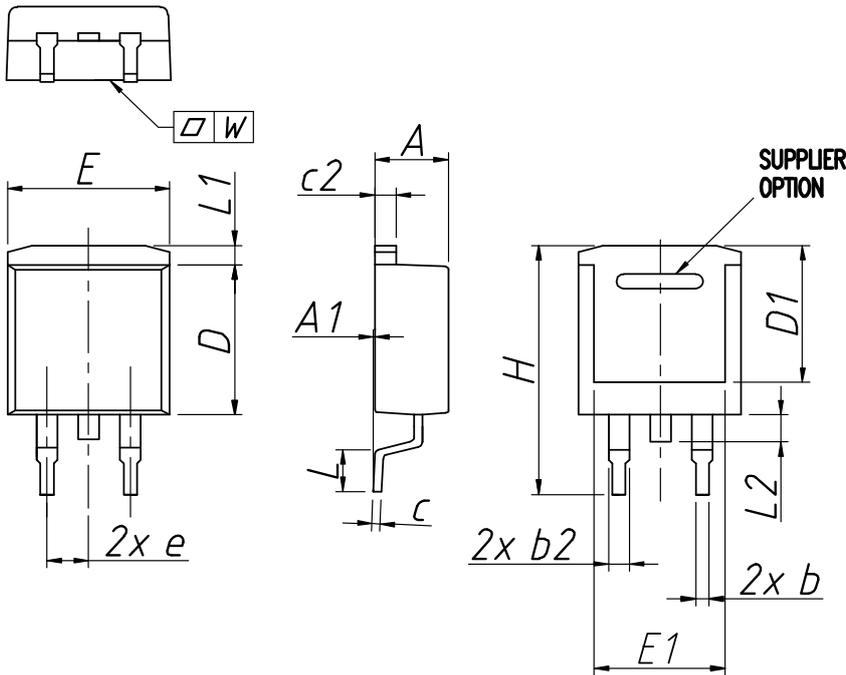
¹⁾ I_{RMS} is typically limited by: 1. pin-to-chip resistance; or by 2. current capability of the chip.
 In case of 1, a common cathode/anode configuration and a non-isolated backside, the whole current capability can be used by connecting the backside.

Product Marking



| Ordering | Part Name | Marking on Product | Delivering Mode | Base Qty | Code Key |
|----------|--------------|--------------------|-----------------|----------|----------|
| Standard | DSSK48-003BS | DSSK48-003BS | Tape & Reel | 800 | 484326 |

| Similar Part | Package | Voltage class |
|--------------|--------------|---------------|
| DSSK48-003B | TO-220AB (3) | 30 |
| DSSK48-0025B | TO-220AB (3) | 25 |

Outlines TO-263 (D2Pak)


| Dim. | Millimeter | | Inches | |
|------|------------|-------|-------------|--------|
| | min | max | min | max |
| A | 4.06 | 4.83 | 0.160 | 0.190 |
| A1 | typ. 0.10 | | typ. 0.004 | |
| b | 0.51 | 0.99 | 0.020 | 0.039 |
| b2 | 1.14 | 1.40 | 0.045 | 0.055 |
| c | 0.40 | 0.74 | 0.016 | 0.029 |
| c2 | 1.14 | 1.40 | 0.045 | 0.029 |
| D | 8.38 | 9.40 | 0.330 | 0.370 |
| D1 | 8.00 | 8.89 | 0.315 | 0.350 |
| E | 9.65 | 10.41 | 0.380 | 0.410 |
| E1 | 6.22 | 8.20 | 0.245 | 0.323 |
| e | 2,54 BSC | | 0,100 BSC | |
| H | 14.61 | 15.88 | 0.575 | 0.625 |
| L | 1.78 | 2.79 | 0.070 | 0.110 |
| L1 | 1.02 | 1.68 | 0.040 | 0.066 |
| L2 | 1.02 | 1.52 | 0.040 | 0.060 |
| W | typ. 0.02 | 0.040 | typ. 0.0008 | 0.0016 |

All dimensions conform with and/or are within JEDEC standard.

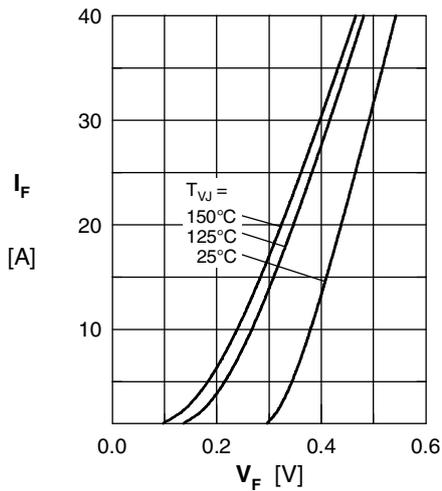


Fig. 1 Maximum forward voltage drop characteristics

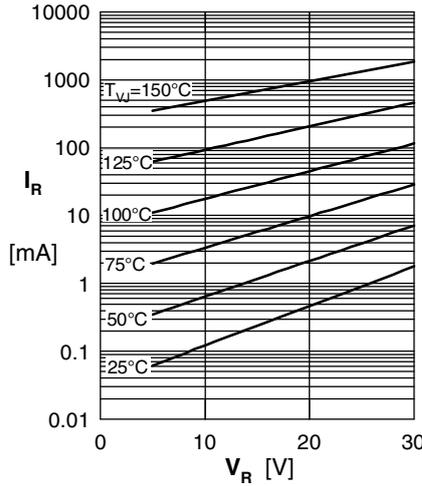


Fig. 2 Typ. reverse current I_R vs. reverse voltage V_R

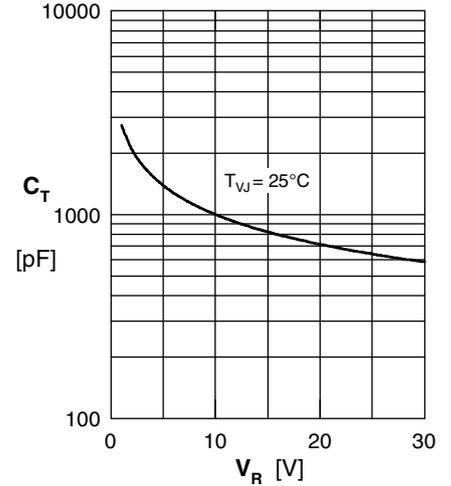


Fig. 3 Typ. junction capacitance C_T vs. reverse voltage V_R

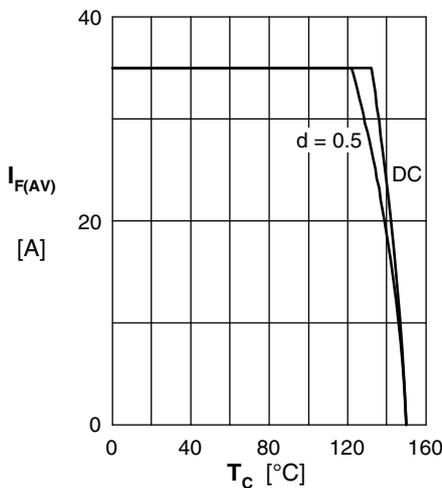


Fig. 4 Average forward current $I_{F(AV)}$ vs. case temperature T_C

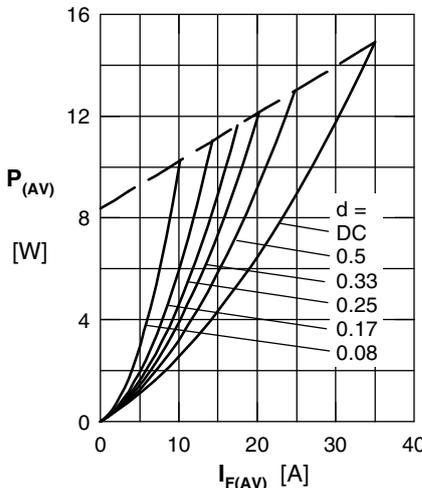


Fig. 5 Forward power loss characteristics

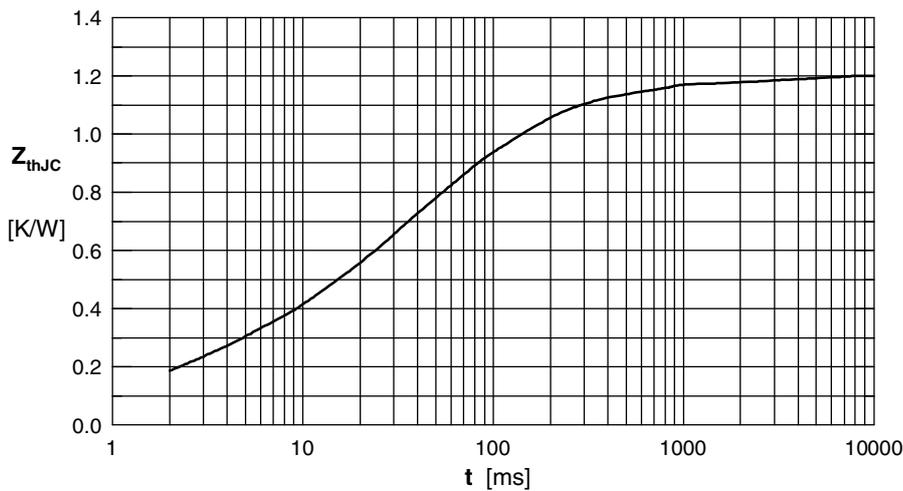


Fig. 6 Transient thermal impedance junction to case at various duty cycles

Note: All curves are per diode